<u>REMARKS</u>

Applicant amended independent claims 1, 9 and 17 for additional clarity.

Rejections Under Sections 102 and 103

Applicant incorporates by reference its remarks filed responsive to the Office Action of March 9, 2005.

In addition, please consider the following. Neither '327 nor '991, either singly or in combination, teaches, discloses or suggests Applicant's invention.

In Tokumaru et. al ('327) reference (column 3 line 1 to 6), the socket apparatus is applied to test semiconductor devices having electrical leads protruding from the sides of the device (either two sides or four sides). In Hornchek et al. (6,541,991) reference, the interface apparatus is applied to test ball grid array integrated devices which has solder balls on the back side of the device. In the present invention, the socket is applied to test semiconductor device which has leads such as pins, solder balls, solder pads, solder columns and the like on the back side of the device.

In Tokumaru et. al. ('327) reference, metallic contactors 3 are arranged on the circumference of the bearer 2 to be brought into contact with the leads 12. (column 3 line 23-25). The resistance of the material used for making the bearer 2 is kept as low value as possible in a range that can sustain the isolating characteristics. (column 4 line 53-55). The present invention discloses that the frame is made of conducting material which has a resistivity of approximately 10⁶ Ohms/sq or less. If the bearer 2 in Tokumaru et. al ('327) reference is built out of a material which has a resistivity of 10⁶ Ohms/sq or less, metallic contactors 3 and the leads 12 are all shorted by contacting with bearer 2. Applicant respectfully submits that the last sentence in Item 7, Paragraph 3 of the Examiner's "Response to Arguments" is not correct. A material at 10¹⁰ to 10¹⁴ Ohms/sq is not conducting.

Entry and reconsideration are respectfully requested.

Respectfully Submitted,

Patrick J. Rafter, et al.